IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~strikethrough~~.

Please REPLACE the paragraph beginning at page 6, line 32, with the following paragraph:

The daughter board 71-1 includes: a daughter-board main body 72-1; the daughter-board male connector 102-1 that is provided at the lower end of the daughter-board main body 72-1; a mounting operation lever 73-1 that is provided at the upper end of the daughter-board main body 72-1; a card edge connector 74-1 that is mounted on a half area 72-1a at the ~~Z2~~ Y2 side of the daughter-board main body 72-1 and connects the memory mounting boards 81-1 to the daughter-board main body 72-1; terminal resistances 75-1 that prevent signal reflections and are mounted on either surface of the other half area 72-1b at the Z1 side of the daughter-board main body 72-1; and bypass capacitors 76-1 that bypass a dielectric layer in the daughter-board main body 72-1, which has a multi-layer structure. Reference numerals 77-1 and 77-2 indicate electronic parts mounting regions to which the terminal resistances 75-1 and the bypass capacitors 76-1 are mounted.

Please REPLACE the paragraph beginning at page 7, line 20, with the following paragraph:

Each of memory mounting boards 81-1 has the end 82-1a insert-connected to the card edge connector 74-1. The memory mounting boards 81-1 protrude horizontally from the half area 72-1a at the ~~Z2~~ Y2 side of the vertically standing daughter board 71-1.

Please REPLACE the paragraph beginning at page 7, line 26, with the following paragraph:

The second board unit 70-2 includes a vertically standing daughter board 71-2 and four memory mounting boards 81-2 that horizontally protrude in a comb-like fashion from the ~~Z1~~Y1-side half of the daughter board 71-2, as shown in FIGS. 6 and 7. The second board unit 70-2 is

substantially the same as the first board unit 70-1, except that the memory mounting boards 81-2 are located on the Z1-side half of the daughter board 71-2.

Please REPLACE the paragraph beginning at page 7, line 35, with the following paragraph:

The daughter board 71-2 includes: a daughter-board main body 72-2; the daughter-board male connector 102-2 that is provided at the lower end of the daughter-board main body 72-2; a lever 73-2 that is provided at the upper end of the daughter-board main body 72-2; a card edge connector 74-2 that is mounted to a half area 72-2b at the Z1 side of the daughter-board main body 72-2 and connects the memory mounting boards 81-2 to the daughter-board main body 72-2; terminal resistances 75-2 that are mounted to the inner surface of a half area 72-2a at the Z2 side of the daughter-board main body 72-2 and both of the surfaces near the end on the Z1 side; and bypass capacitors 76-2. Reference numerals 78-1~~,~~ and 78-2~~, and 78-3~~ indicate electronic parts mounting regions to which the terminal resistances 75-2 and the bypass capacitors 76-2 are mounted.

Please REPLACE the paragraph beginning at pages 8, line 22, with the following paragraph:

Each of the memory mounting boards 81-2 has the end 82-2a insert-connected to the card edge connector 74-2. The memory mounting boards 81-2 horizontally protrude from the half area ~~72-2a~~72-2b at the ~~Z1~~ YI side of the vertically standing daughter board 71-2.

Please REPLACE the paragraph beginning at page 10, line 3, with the following paragraph:

As the memory mounting boards 81-1 of the first board unit ~~71-1~~70-1 face the memory mounting boards 81-2 of the second board unit ~~71-2~~70-2, and vice versa, the distance between the daughter board ~~72-1~~71-1 of the first board unit ~~71-1~~70-1 and the daughter board ~~72-2~~72-1 of the second board unit ~~71-2~~70-2 is W, which is also the same as that in a structure having only one board unit. Therefore, it is not necessary to increase the width of a multiprocessor into which a plural number of memory assemblies 50 are to be incorporated. Thus, a large number of memory assemblies 50 can be incorporated into a multiprocessor of a size that can be accommodated in a rack.

Please REPLACE the paragraph beginning at page 10, line 17, with the following paragraph:

2) Ready-made devices can serve as the daughter-board connector devices 100-1 and 100-2.

The number of the memory mounting boards 81-1 of the first board unit ~~71-1~~70-1 and the number of the memory mounting boards 81-2 of the second board unit ~~71-2~~70-2 are the same as the number of the memory mounting boards of a conventional board unit. Accordingly, the number of terminals in each of the connectors 102-1 and 102-2 of the first and second board units ~~71-1~~70-1 and ~~71-2~~70-2 is the same as that of a conventional board unit, and standard connector devices can be employed. Thus, the production cost of the memory assembly 50 can be low.

Please REPLACE the paragraph beginning at page 11, line 34, with the following paragraph:

In FIG. 8, the block 117 has the memory assembly 50 pulled out. The levers 73-1 and 73-2 are rotated to be partially engaged with the frame 114, so that the first board unit ~~71-1~~70-1 and the second board unit ~~71-2~~70-2 are pushed down toward the Z2 side and are then mounted. At a time of maintenance, the first board unit 70-1 and the second board unit 70-2 are pulled up toward the Z1 side and are then removed.